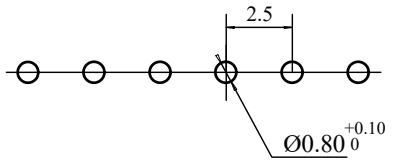
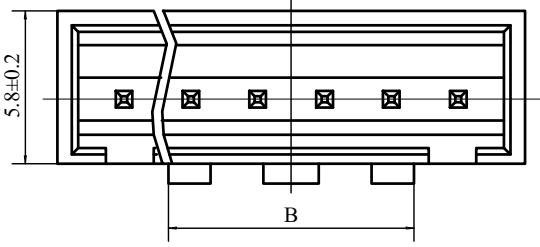
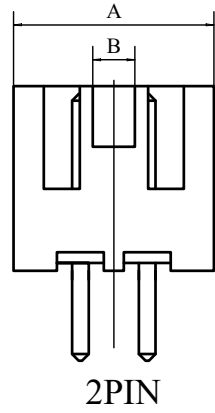
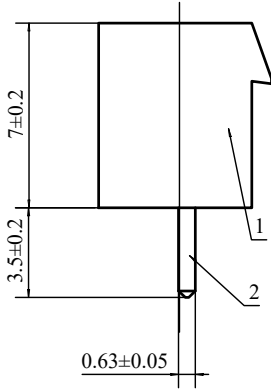


REV.	EC#	DESCRIPTION	DATE DRAWN	CHECK	APPROVED
1.00		初版发行	2020-8-28	瞿寿坤	胡海萍

NUMBER OF PINS	DIM.A	DIM.B
15P	40	31.3
14P	37.5	28.8
13P	35	26.3
12P	32.5	23.8
11P	30	21.3
10P	27.5	18.8
9P	25	16.3
8P	22.5	13.8
7P	20	11.3
6P	17.5	8.8
5P	15	6.3
4P	12.5	3.6
3P	10	2.6
2P	7.5	2.6



PCB LAYOUT

技术要求:

- 1) 材质: 见附表;
- 2) 电镀: 见附表;
- 3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
- 4) 端子表面无氧化、电镀不良等现象。

适应基板厚度: 1.2mm~1.6mm
 温度范围: -25°C~85°C
 额定电压: 250V AC/DC
 额定电流: 3A
 接触电阻: ≤0.01 Ω
 绝缘电阻: ≥1000M Ω
 耐 压: 1000V AC/minute

2	PIN	n PCS	材质: 黄铜, 电镀: 镀亮锡
1	Housing	1 PCS	材质: PA66, 颜色: 白色
NO.	NAME	Q'TY	DESCRIPTION

深圳市虹成电子有限公司

DRAW:	瞿寿坤	2020-8-28	TITLE: WAFER 2.5XHBA 立式 DIP	HC-XHB-7A-TW
DESIGN:	瞿寿坤	2020-8-28		
CHECK:	胡海萍	2020-8-28	SERIES: 1501 SERIES	DRAW NO.
APPROVED	胡海萍	2020-8-28	P/N:	
CUSTOMER DRAWING			REV. 1.00	SCALE N/A
UNIT:	mm	SHEET:	1/1	

GENERAL TOLERANCES			
DIM	TOL	DIM	DEG
X.		X°	±3.00°
X.X	±0.35	X.X°	±2.00°
X.XX	±0.25	X.XX°	±1.00°
X.XXX	±0.15	X.XXX°	